



## Material Content Data Sheet



<b>Sales Product Name</b>		IPP100N08S2L-07		<b>Issued</b>		25. January 2018		
<b>MA#</b>		MA001659884						
<b>Package</b>		PG-TO220-3-1		<b>Weight*</b>		2040.90 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.294	0.60	0.60	6024	6024
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		400	
	non noble metal	copper	7440-50-8	815.335	39.95	40.00	399497	400017
	non noble metal	aluminium	7429-90-5	7.941	0.39	0.39	3891	3891
wire	non noble metal	aluminium	7429-90-5	7.941	0.39	0.39	3891	3891
encapsulation	organic material	carbon black	1333-86-4	8.769	0.43		4297	
	plastics	epoxy resin	-	96.464	4.73		47265	
	inorganic material	silicondioxide	60676-86-0	479.397	23.49	28.65	234895	286457
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10516	10516
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121
solder	non noble metal	tin	7440-31-5	0.154	0.01		75	
	noble metal	silver	7440-22-4	0.192	0.01		94	
	non noble metal	lead	7439-92-1	7.350	0.36	0.38	3602	3771
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	iron	7439-89-6	0.590	0.03		289	
	non noble metal	copper	7440-50-8	589.466	28.88	28.92	288827	289203
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com